

AMENDMENT TO THE CLAIMS

Please amend the claims by replacing them with the following complete listing of claims:

Claims 1 – 10. (*Canceled*)

Claim 11. (*Currently Amended*) An arrangement for increasing a packing density on a printed circuit with surface mounted electrical components the printed circuit comprising:

two films pressed against one another with a dielectric arranged between them; and

~~at least one of~~ mutually opposite faces of the films being fitted with surface mounted electrical components so that the electrical components are mutually opposite, via holes being provided in the printed ~~circuit to~~ circuit to connect the two films,

wherein each via hole of the via holes ~~[[are]]~~ is a direct connection between the mutually opposite faces of the films.

Claim 12. (*Previously Presented*) The arrangement as claimed in claim 11, further comprising further surface mounted electrical components arranged on faces of the two films which are not mutually opposite.

Claim 13. (*Previously Presented*) The arrangement as claimed in claim 11, further comprising a further layer of a dielectric and a further film being applied to at least one face of the printed circuit.

Claim 14. (*Previously Presented*) The arrangement as claimed in claim 11, wherein the two films contain copper.

Claim 15. (*Previously Presented*) The arrangement as claimed in claim 11, further comprising first contacts formed on at least one face of the printed circuit.

Claim 16. (*Previously Presented*) The arrangement as claimed in claim 13, wherein the via holes are formed between the two films and the further film.

Claim 17. (*Previously Presented*) The arrangement as claimed in claim 11, wherein the surface mounted electrical components are resistors, coils or capacitors.

Claim 18. (*Previously Presented*) The stack having a plurality of printed circuits as claimed in claim 11 arranged one on top of another.

Claim 19. (*Previously Presented*) The arrangement as claimed in claim 14, wherein the via holes are formed between the two films and a further film.

Claim 20. (*Previously Presented*) The arrangement as claimed in claim 15, wherein the via holes are formed between the two films and a further film.

Claim 21. (*Previously Presented*) The arrangement as claimed in claim 11, wherein the two films are compressed films.

Claim 22. (*Currently Amended*) A process for fabricating a printed circuit, comprising:

providing two films against one another, the two films having mutually opposite faces;

arranging a dielectric between the two films; and

fitting ~~at least one of~~ the mutually opposite faces of the films with surface mounted electrical components and via holes, so that the electrical components are mutually opposite;

wherein each via hole of the via holes ~~[[are]]~~ is arranged in direct connection between the mutually opposite faces of the films.

Claim 23. (*Previously Presented*) The process as claimed in claim 22, further comprising providing a further layer of dielectric and a further film applied to at least one face of the two films.

Claim 24. (*Previously Presented*) The process as claimed in claim 22, wherein the via holes are microvias.

Claim 25. (*Previously Presented*) The process as claimed in claim 22, wherein the via holes are produced by one of drilling, electroplating and etching processes.

Claim 26. (*Previously Presented*) The process as claimed in claim 22, further comprising pressing together the two films.

Claim 27. (*Previously Presented*) The process as claimed in claim 22, further comprising arranging further surface mounted electrical components on faces of the two films which are not mutually opposite.

Claim 28. (*Previously Presented*) The process as claimed in claim 22, further comprising embedding the surface mounted electrical components in the dielectric.

Claim 29. (*Previously Presented*) The process as claimed in claim 22, further comprising soldering the surface mounted electrical components to the two films.

Claim 30. (*Previously Presented*) The process as claimed in claim 22, further comprising providing first contacts which are formed on at least one face of the two films such that electrical connections are made to another printed circuit.